



13th July, 2026

To,
National Stock Exchange of India Ltd
Exchange Plaza, 5th Floor,
Plot No. C/1, G block,
Bandra-Kurla Complex,
Bandra (E), Mumbai 400051.
Scrip ID - HPAL

To,
BSE Limited
1st Floor, New Trading Ring,
Rotunda Building,
Phiroze Jeejeebhoy Towers,
Dalal Street, Mumbai 400001.
Scrip Code - 543433

Sub : Outcome of the board meeting under Regulation 30 of the Securities and Exchange Board of India (Listing Obligation and Disclosure Requirements) Regulations, 2015 ("Listing Regulations").

Dear Sir/Madam,

This is to inform that the Board of Directors of the Company at their meeting held today, i.e., on July 13, 2026, *inter alia*, considered and approved availing of Working Capital Term Loan (ECLGS) of Rs. 21.6 million at 9% p.a. for a total tenure of 5 years with 1 year moratorium of principal payments from ICICI Bank Limited.

The meeting commenced at 04:00 p.m. and concluded at 04:30 p.m.

This information is also being uploaded on the website of the Company i.e. www.hpadhesives.com under the Investor relations section.

You are requested to take the above information on record.

Thanking you.

For HP Adhesives Limited

Swati Talgaonkar
Company Secretary
ACS30463
Encl.: As above

HP ADHESIVES LIMITED (Formerly known as HP ADHESIVES PRIVATE LIMITED)

Corporate Office: 501, 5th floor, C Wing, Business Square Bldg., Andheri East, Mumbai 400093, Maharashtra, India
Registered Office: 11, Unique House, Chakala, Andheri (East), Mumbai 400099, India
CIN: L24304MH2019PLC325019

Tel: +91-22-68196300
Email: info@hpadhesives.com
Web: www.hpadhesives.com